General Description

The WSD2068 is the highest performance trench N-ch MOSFETs with extreme high cell density , which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WSD2068 meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

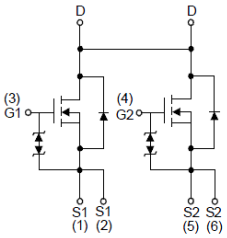
Product Summery

BV_{DSS}	R_{DSON}	I_D
20V	15.5mΩ	7.5A

Applications

- Power Management in Notebook Computer, Portable Equipment and Battery Powered Systems.
- DC-DC Power System
- ESD:2KV

DFN2X3A_EP Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	±12	V
I_D@T_A=25℃	Continuous Drain Current, V_{GS} @ 4.5V[1]	7.5	A
I_D@T_A=70℃	Continuous Drain Current, V_{GS} @ 4.5V[1]	6.5	A
I_{DM}	Pulsed Drain Current[2]	30	A
P_D@T_A=25℃	Total Power Dissipation[3]	1.5	W
P_D@T_A=70℃	Total Power Dissipation[3]	1.0	W
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient [1] (Steady State)	---	120	℃/W
$R_{\theta JA}$	Thermal Resistance Junction-ambient [1] (t<10S)	---	83	℃/W

Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

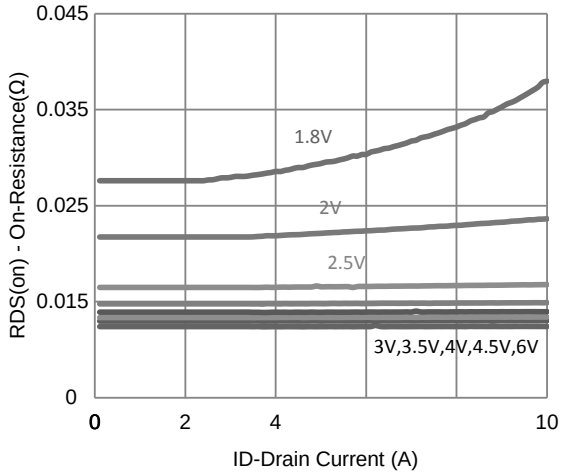
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	20	---	---	V
$\triangle BV_{DSS}/\triangle T_J$	BVDSS Temperature Coefficient	Reference to 25℃ , I_D=1mA	---	0.022	---	V/℃
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=4.5V , I_D=5.5A	---	12	15.5	mΩ
		V_{GS}=2.5V , I_D=5.5A	---	16	20	
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	0.3	0.7	1.0	V
$\triangle V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-2.32	---	mV/℃
I_{DSS}	Drain-Source Leakage Current	V_{DS}=16V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=16V , V_{GS}=0V , T_J=55℃	---	---	5	
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±12V , V_{DS}=0V	---	---	±100	nA
gfs	Forward Transconductance	V_{DS}=5V , I_D=10A	---	20	---	S
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	11	---	Ω
Q_g	Total Gate Charge (4.5V)	V_{DS}=10V , V_{GS}=4.5V , I_D=5A	---	15	20	nC
Q_{gs}	Gate-Source Charge		---	2.2	---	
Q_{gd}	Gate-Drain Charge		---	4.2	---	
$T_{d(on)}$	Turn-On Delay Time	V_{DS}=10V , V_{GS}=10V , R_G=6Ω, I_D=5A ,RL=2Ω	---	148	---	ns
T_r	Rise Time		---	277	---	
$T_{d(off)}$	Turn-Off Delay Time		---	1616	---	
T_f	Fall Time		---	751	---	
C_{iss}	Input Capacitance	V_{DS}=10V , V_{GS}=0V , f=1MHz	---	1219	---	pF
C_{oss}	Output Capacitance		---	150	---	
C_{rss}	Reverse Transfer Capacitance		---	123	---	

Diode Characteristics

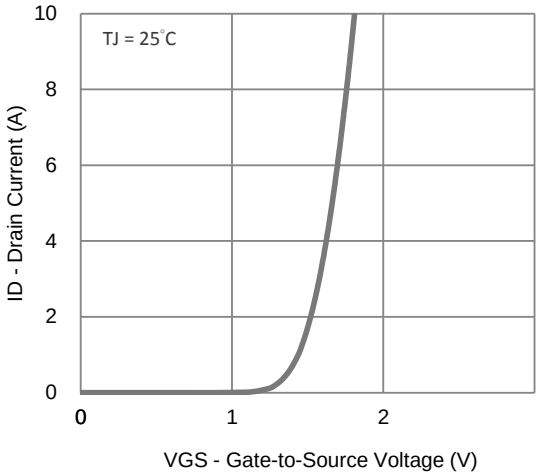
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current[1,4]	V_G=V_D=0V , Force Current	---	---	5	A
I_{SM}	Pulsed Source Current[2,4]		---	---	15	A
V_{SD}	Diode Forward Voltage[2]	V_{GS}=0V , I_S=1A , T_J=25℃	---	0.76	1.3	V
t_{rr}	Reverse Recovery Time	I_F=5A,dI/dt=100A/μs , T_J=25℃	---	245	---	nS
Q_{rr}	Reverse Recovery Charge		---	1105	---	nC

Note :
1.The data tested by surface mounted on a 1 inch^2 FR-4 board with 2OZ copper, t<10sec.
2.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%
3.The power dissipation is limited by 150℃ junction temperature
4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

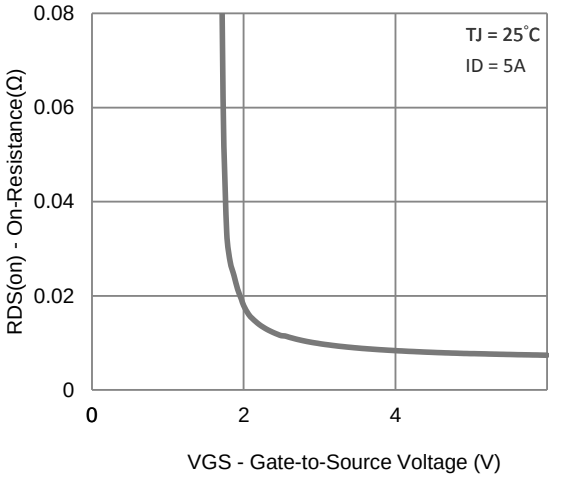
Typical Characteristics



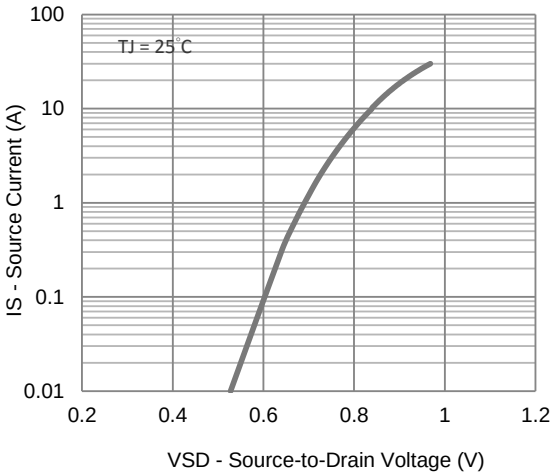
1. On-Resistance vs. Drain Current



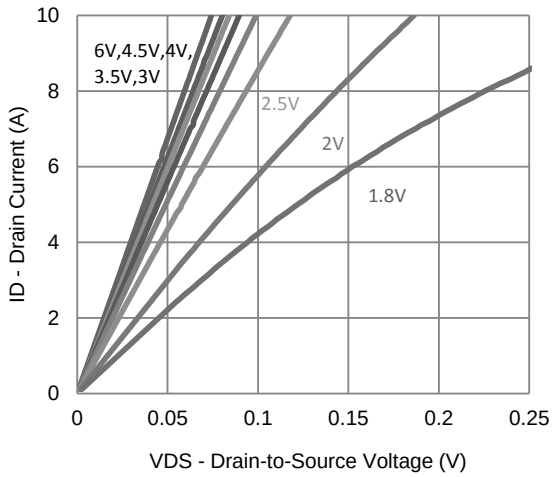
2. Transfer Characteristics



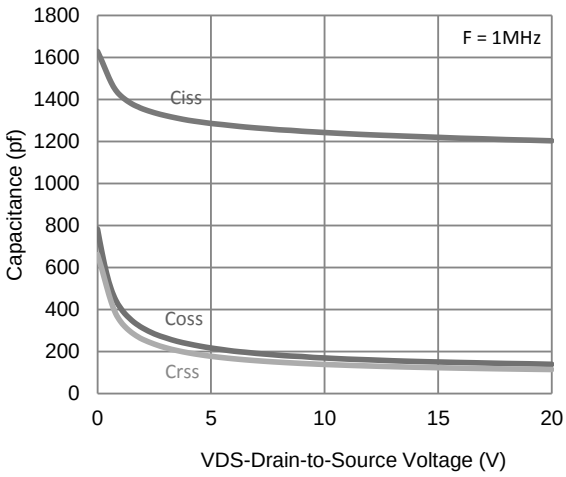
3. On-Resistance vs. Gate-to-Source Voltage



4. Drain-to-Source Forward Voltage

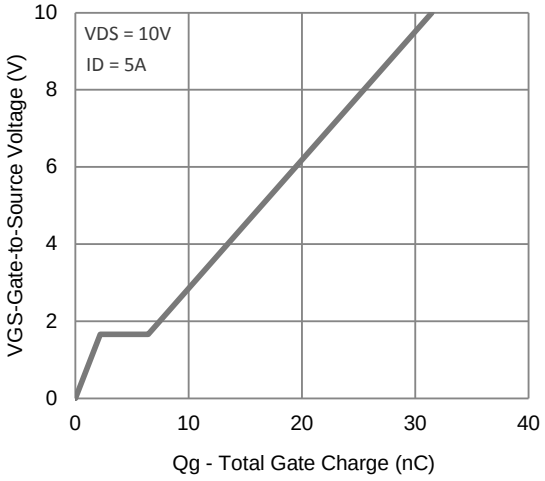


5. Output Characteristics

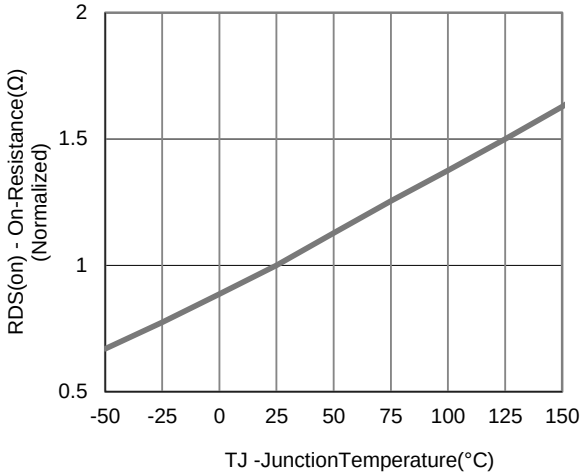


6. Capacitance

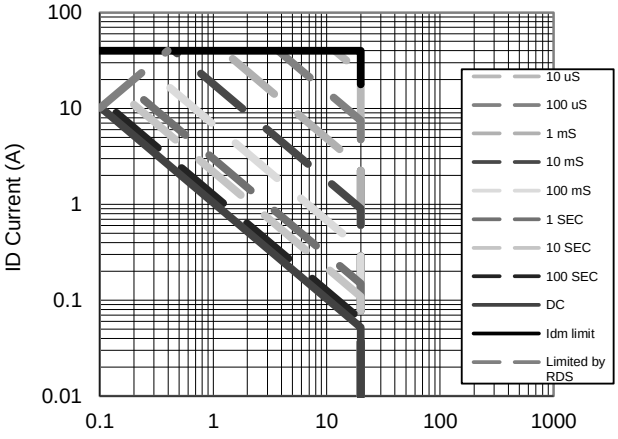
Typical Characteristics



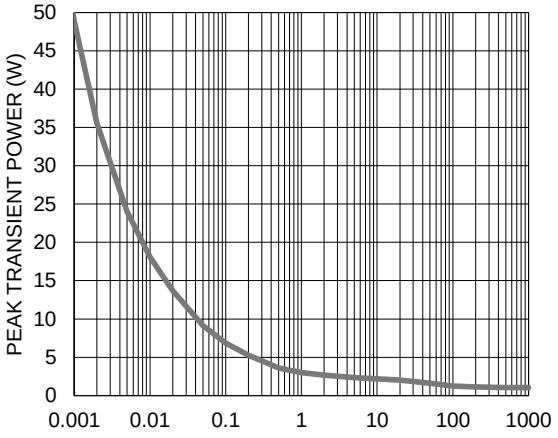
7. Gate Charge



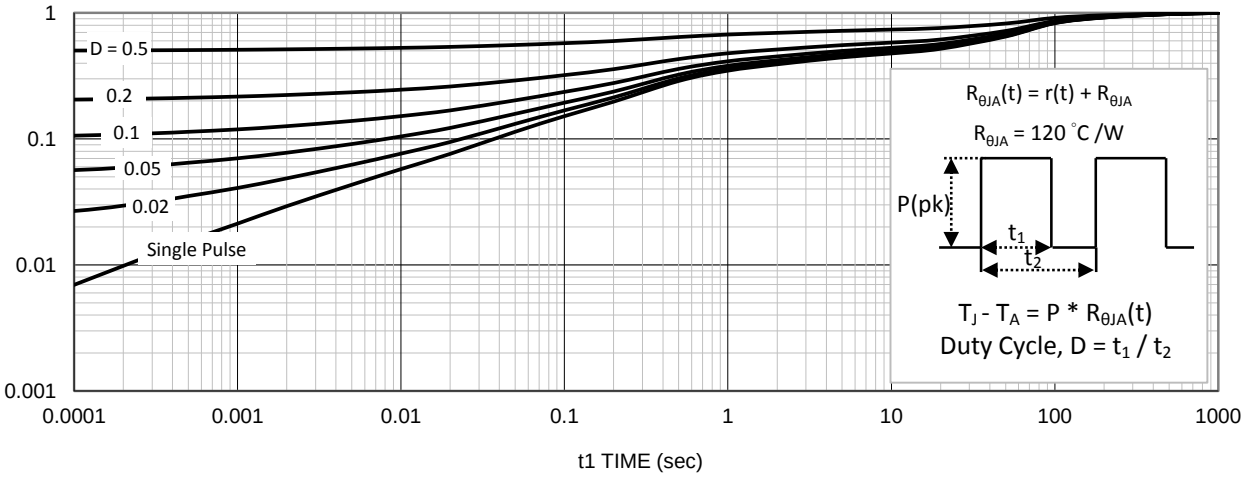
8. Normalized On-Resistance Vs Junction Temperature



9. Safe Operating Area

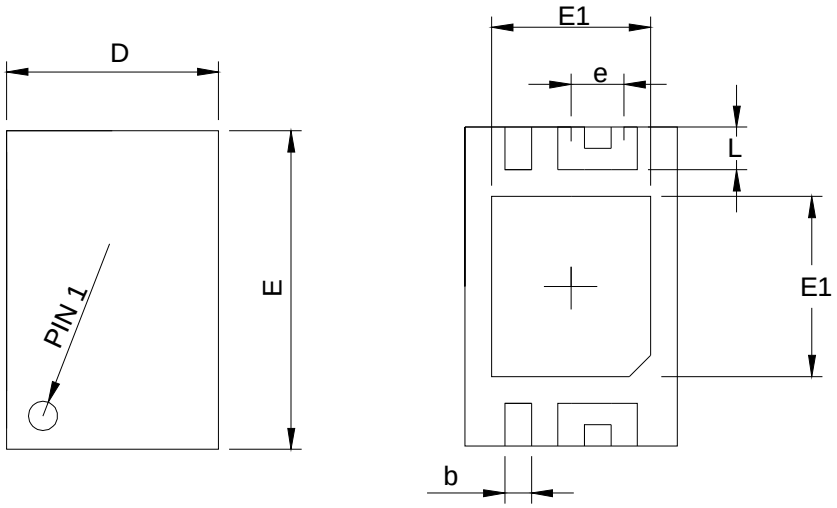


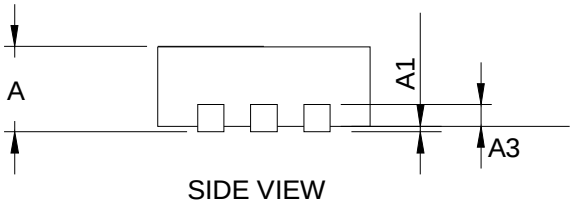
10. Single Pulse Maximum Power Dissipation



11. Normalized Thermal Transient Junction to Ambient

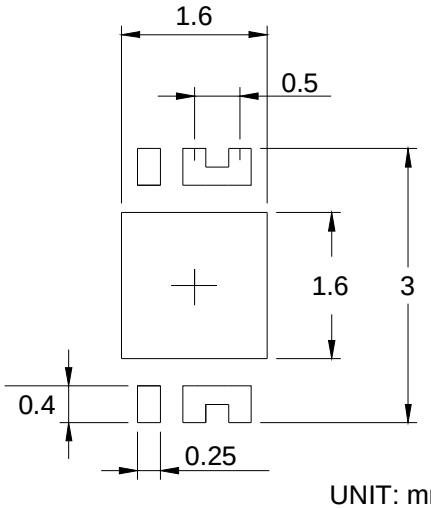
Package Information DFN2x3A-6_EP





SYMBOL	DFN2x3A-6_EP			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.70	1.00	0.028	0.039
A1	0.00	0.05	0.000	0.002
A3	0.203 REF		0.008 REF	
b	0.20	0.30	0.008	0.012
D	1.90	2.10	0.075	0.083
E1	1.60	1.80	0.063	0.071
E	2.90	3.10	0.114	0.122
D1	1.40	1.60	0.055	0.063
e	0.50 BSC		0.02 BSC	
L	0.30	0.50	0.012	0.020

RECOMMENDED LAND PATTERN



UNIT: mm

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